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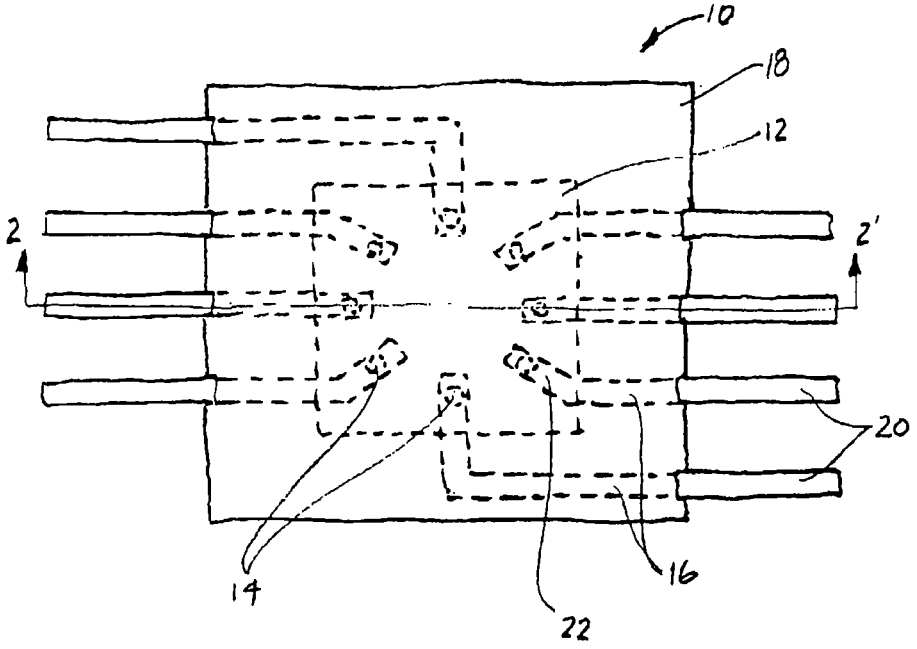
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(54) Title: FLIP CHIP-IN-LEADFRAME PACKAGE AND PROCESS



(57) Abstract: A method for connecting a chip to a leadframe (16) includes forming bumps (14) on a die (12) by a Au stud-bumping technique, and attaching the chip to the leadframe (16) by thermo-compression of the bumps (14) onto bonding fingers (22) of the leadframe (16). Also a flip chip-in-leadframe package (10) is made according to the method. The package (10) provides improved electrical performance particularly for devices used in RF applications.

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